2-Input OR Gate/CMOS Logic Level Shifter

The MC74VHC1GT32 is an advanced high speed CMOS 2–input OR gate fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The device input is compatible with TTL-type input thresholds and the output has a full 5 V CMOS level output swing. The input protection circuitry on this device allows overvoltage tolerance on the input, allowing the device to be used as a logic–level translator from 3.0 V CMOS logic to 5.0 V CMOS Logic or from 1.8 V CMOS logic to 3.0 V CMOS Logic while operating at the high–voltage power supply.

The MC74VHC1GT32 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage. This allows the MC74VHC1GT32 to be used to interface 5 V circuits to 3 V circuits. The output structures also provide protection when $V_{\rm CC}=0$ V. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

- High Speed: tpD = 3.5 ns (Typ) at VCC = 5 V
- Low Power Dissipation: $I_{CC} = 2 \mu A$ (Max) at $T_A = 25^{\circ}C$
- TTL-Compatible Inputs: V_{IL} = 0.8 V; V_{IH} = 2.0 V
- CMOS-Compatible Outputs: VOH > 0.8 VCC; VOL < 0.1 VCC @Load
- Power Down Protection Provided on Inputs and Outputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 65; Equivalent Gates = 15

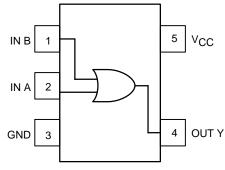


Figure 1. Pinout (Top View)

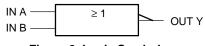
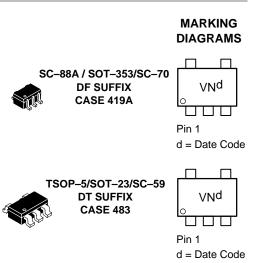


Figure 2. Logic Symbol



ON Semiconductor™

http://onsemi.com



PIN ASSIGNMENT						
1	IN B					
2	IN A					
3	GND					
4	OUT Y					
5	Vcc					

FUNCTION TABLE

Inp	uts	Output		
Α	В	Y		
L	L	L		
L	Н	Н		
Н	L	Н		
Н	Н	Н		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS (Note 1)

Symbol	Characteristics	Value	Unit
Vcc	DC Supply Voltage	-0.5 to +7.0	V
VIN	DC Input Voltage	-0.5 to +7.0	V
VOUT	DC Output Voltage $V_{CC} = 0$ High or Low State	−0.5 to 7.0 −0.5 to V _{CC} + 0.5	V
ΙΚ	Input Diode Current	-20	mA
lok	Output Diode Current V _{OUT} < GND; V _{OUT} > V _{CC}	+20	mA
lout	DC Output Current, per Pin	+25	mA
ICC	DC Supply Current, V _{CC} and GND	+50	mA
PD	Power dissipation in still air SC–88A, TSOP–5	200	mW
θЈА	Thermal resistance SC-88A, TSOP-5	333	°C/W
TL	Lead temperature, 1 mm from case for 10 s	260	°C
TJ	Junction temperature under bias	+150	°C
T _{stg}	Storage temperature	-65 to +150	°C
VESD	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{Latch-Up}	Latch–Up Performance Above V _{CC} and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those
indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional
operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit	
Vcc	DC Supply Voltage		3.0	5.5	V
VIN	DC Input Voltage	0.0	5.5	V	
VOUT	DC Output Voltage	V _{CC} = 0 High or Low State	0.0 0.0	5.5 VCC	V
TA	Operating Temperature Range		- 55	+125	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 3.3 V ± 0.3 V V _{CC} = 5.0 V ± 0.5 V	0	100 20	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

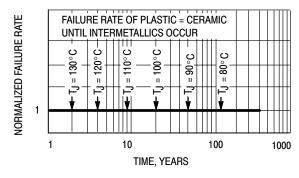


Figure 3. Failure Rate vs. Time Junction Temperature

^{2.} Tested to EIA/JESD22-A114-A

^{3.} Tested to EIA/JESD22-A115-A

^{4.} Tested to JESD22-C101-A

^{5.} Tested to EIA/JESD78

DC ELECTRICAL CHARACTERISTICS

			VCC	T	T _A = 25°C		T _A ≤ 85°C		-55 ≤ T _A ≤ 125°C		
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
VIH	Minimum High–Level Input Voltage		3.0 4.5 5.5	1.4 2.0 2.0			1.4 2.0 2.0		1.4 2.0 2.0		V
V _{IL}	Maximum Low–Level Input Voltage		3.0 4.5 5.5			0.53 0.8 0.8		0.53 0.8 0.8		0.53 0.8 0.8	٧
VOH	Minimum High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OH} = -50 μA	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
	VIN = VIH or VIL	VIN = VIH or VIL IOH = -4 mA IOH = -8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		٧
V _{OL}	Maximum Low–Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OL} = 50 μA	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	V
	V _{IN} = V _{IH} or V _{IL}	V _{IN} = V _{IH} or V _{IL} I _{OL} = 4 mA I _{OL} = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	٧
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			2.0		20		40	μΑ
ICCT	Quiescent Supply Current	Input: V _{IN} = 3.4 V	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0.0			0.5		5.0		10	μΑ

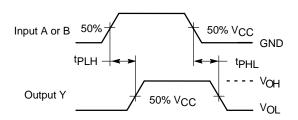
AC ELECTRICAL CHARACTERISTICS ($C_{load} = 50 \text{ pF}$, Input $t_f = t_f = 3.0 \text{ns}$)

				T _A = 25°C		T _A ≤ 85°C		$-55 \le T_{\mbox{\scriptsize A}} \le 125^{\circ}\mbox{\scriptsize C}$			
Symbol	Parameter	Test Condit	ions	Min	Тур	Max	Min	Max	Min	Max	Unit
tp _{LH} , Maximum tp _{HL} Propogation Delay,		V _{CC} = 3.3 ± 0.3 V	C _L = 15 pF C _L = 50 pF		4.8 6.1	7.9 11.4		9.5 13.0		11.5 15.5	ns
Input A or B to Y	$V_{CC} = 5.0 \pm 0.5 \text{ V}$	C _L = 15 pF C _L = 50 pF		3.7 4.4	5.5 7.5		6.5 8.5		8.0 10.0		
C _{IN}	Maximum Input Capacitance				5.5	10		10		10	pF

CpD Power Dissipation Capacitance (Note 6)

6. CpD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: ICC(OPR) = CpD • V_{CC} • f_{in} + I_{CC}. CpD is used to determine the no–load dynamic power consumption; PD = CpD • V_{CC} • f_{in} + I_{CC} • V_{CC}.

Typical @ 25°C, $V_{CC} = 5.0 \text{ V}$



DEVICE UNDER TEST CL*

*Includes all probe and jig capacitance

Figure 4. Switching Waveforms

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

	Device Nomenclature							
Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type	Tape and Reel Size
MC74VHC1GT32DFT1	MC	74	VHC1G	T32	DF	T1	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1GT32DFT2	MC	74	VHC1G	T32	DF	T2	SC-88A / SOT-353 / SC-70	178 mm (7") 3000 Unit
MC74VHC1GT32DTT1	MC	74	VHC1G	T32	DT	T1	TSOPS / SOT-23 / SC-59	178 mm (7") 3000 Unit

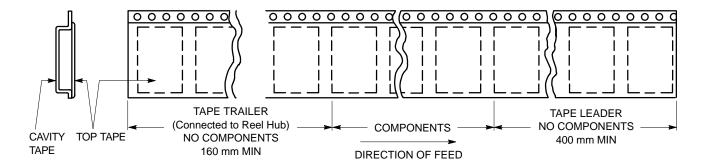


Figure 6. Tape Ends for Finished Goods

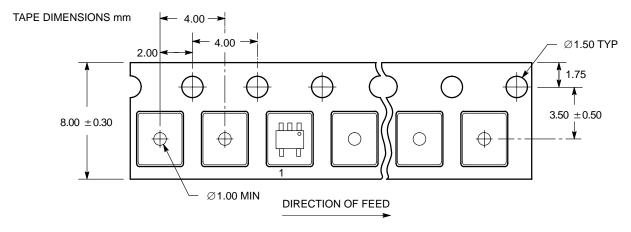


Figure 7. SC-70-5/SC-88A/SOT-353 DFT1 Reel Configuration/Orientation

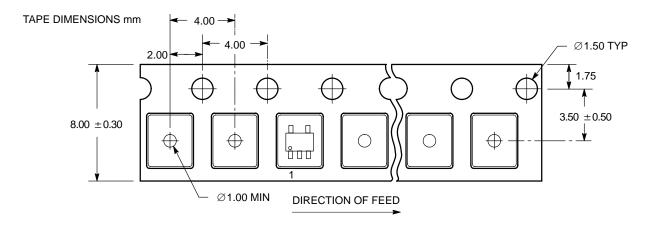


Figure 8. SC-70/SC-88A/SOT-353 DFT2 and SOT23-5/TSOP-5/SC59-5 DTT1 Reel Configuration/Orientation

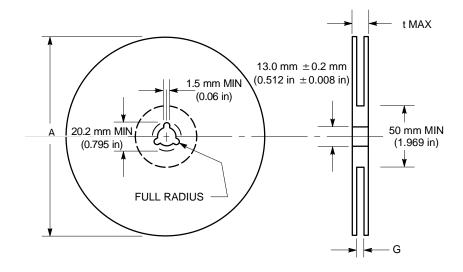


Figure 9. Reel Dimensions

REEL DIMENSIONS

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

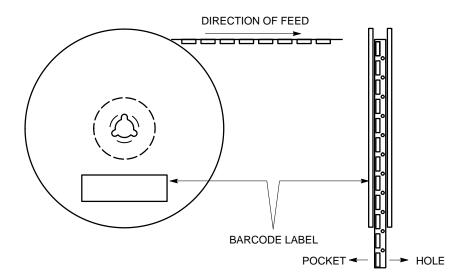
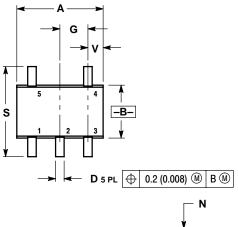


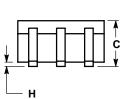
Figure 10. Reel Winding Direction

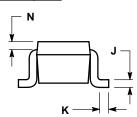
PACKAGE DIMENSIONS

SC-88A/SOT-353/SC-70 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-01 ISSUE E

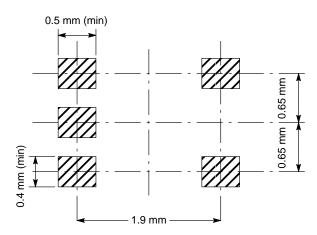






- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

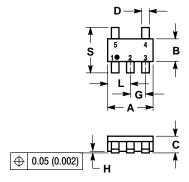
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
C	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
_	0.004	0.010	0.10	0.25	
Κ	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20	REF	
S	0.079	0.087	2.00	2.20	
٧	0.012	0.016	0.30	0.40	

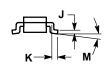


PACKAGE DIMENSIONS

TSOP-5/SOT-23/SC-59 DT SUFFIX

5-LEAD PACKAGE CASE 483-01 ISSUE A

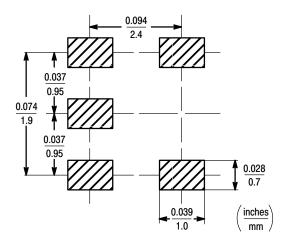




NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- 2. GONTHOCHING DIMINISTRATION MILLIMISTER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIN	IETERS	INCHES					
DIM	MIN	MAX	MIN	MAX				
Α	2.90	3.10	0.1142	0.1220				
В	1.30	1.70	0.0512	0.0669				
С	0.90	1.10	0.0354	0.0433				
D	0.25	0.50	0.0098	0.0197				
G	0.85	1.00	0.0335	0.0413				
Н	0.013	0.100	0.0005	0.0040				
7	0.10	0.26	0.0040	0.0102				
K	0.20	0.60	0.0079	0.0236				
L	1.25	1.55	0.0493	0.0610				
M	0 °	10°	0°	10°				
S	2.50	3.00	0.0985	0.1181				



ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.